



RE440-LF

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Hot air leveling (HAL-leadfree)
- Surface with component print and soldering stop mask
- Staggered hole grid 2.54 x 2.54 mm, thus duplication of the borings (interstitial)
- Soldering pads 1.40 mm Ø
- 4304 holes 0.80 mm Ø
- Particularly appropriate for PGA sockets in staggered grid 2.54 x 2.54 mm
- Connector 32/64/96-channel DIN 41612 type C
- Working temperature max. 150 °C
- Solder bath proof: 260 °C > 50 Sec.
- Size 100 x 160 mm